

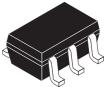
**Vishay Semiconductors** 

# Dual - MOSMIC®- two AGC Amplifiers for TV-Tuner Prestage with 5 V Supply Voltage

#### **Comments**

MOSMIC - MOS Monolithic Integrated Circuit





16903



Electrostatic sensitive device.

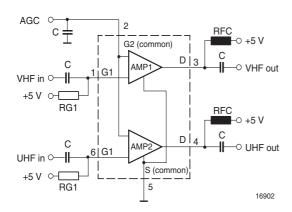
Observe precautions for handling.

#### **Features**

- Easy Gate 1 switch-off with PNP switching transistors inside PLL
- Two differently optimized amplifiers in a single package
- · Integrated gate protection diodes
- Low noise figure, high gain
- Typical forward transadmittance of 31 mS resp 28 mS
- · Partly internal self biasing-network on chip
- · Superior cross modulation at gain reduction
- · High AGC-range with soft slope
- Main AGC control range from 3 V to 0.5 V
- Supply voltage 5 V (3 V to 7 V)
- · SMD package, standard pinning

## **Applications**

Low noise gain controlled VHF and UHF input stages, such as in digital and analog TV tuners.



#### **Mechanical Data**

Weight: 6 mg Case: SOT 363

V - Vishay

Y - Year, is variable for digit from 0 to 9

(e.g. 0 = 2000, 1 = 2001)

CW - Calendar Week, is variable for number

from 01 to 52

Number of Calendar Week is always indicating

place of pin 1

#### **Pinning:**

1 = Gate 1 (amplifier 1), 2 = Gate 2,

3 = Drain (amplifier 1), 4 = Drain (amplifier 2),

5 = Source, 6 = Gate1 (amplifier 2)

# **TSDF02830Y**

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#### **Parts Table**

Part	Marking	Package
TSDF02830Y	WM2	SOT363

#### **Absolute Maximum Ratings**

T<sub>amb</sub> = 25 °C, unless otherwise specified

#### **Amplifier 1**

Following data are valid for operating amplifier 1(pin 1, 3, 2, 5) which is optimized for VHF applications

Parameter	Test condition	Symbol	Value	Unit
Drain - source voltage		V <sub>DS</sub>	8	V
Drain current		I <sub>D</sub>	30	mA
Gate 1/Gate 2 - source peak current		± I <sub>G1/G2SM</sub>	10	mA
Gate 1 - source voltage		+ V <sub>G1SM</sub>	6	V
		- V <sub>G1SM</sub>	1.5	V
Gate 2 - source voltage		± V <sub>G2SM</sub>	6	V
Total power dissipation	T <sub>amb</sub> ≤ 60 °C	P <sub>tot</sub>	200	mW
Channel temperature		T <sub>Ch</sub>	150	°C
Storage temperature range		T <sub>stg</sub>	- 55 to + 150	°C
Channel ambient	on glass fibre printed board (25 x 20 x 1.5) mm <sup>3</sup> plated with 35 μm Cu	R <sub>thChA</sub>	450	K/W

#### **Amplifier 2**

Following data are valid for operating amplifier 2 (pin 6, 4, 2, 5) which is optimized for UHF applications

Parameter	Test condition	Symbol	Value	Unit
Drain - source voltage		V <sub>DS</sub>	8	V
Drain current		I <sub>D</sub>	25	mA
Gate 1/Gate 2 - source peak current		± I <sub>G1/G2SM</sub>	10	mA
Gate 1 - source voltage		+ V <sub>G1SM</sub>	6	V
		- V <sub>G1SM</sub>	1.5	V
Gate 2 - source voltage		± V <sub>G2SM</sub>	6	V
Total power dissipation	T <sub>amb</sub> ≤ 60 °C	P <sub>tot</sub>	200	mW
Channel temperature		T <sub>Ch</sub>	150	°C
Storage temperature range		T <sub>stg</sub>	- 55 to + 150	°C
Channel ambient	on glass fibre printed board (25 x 20 x 1.5) mm <sup>3</sup> plated with 35 µm Cu	R <sub>thChA</sub>	450	K/W

#### **Electrical DC Characteristics**

 $T_{amb}$  = 25 °C, unless otherwise specified

#### **Amplifier 1**

Following data are valid for operating amplifier 1(pin 1, 3, 2, 5) which is optimized for VHF applications

Parameter	Test condition	Symbol	Min	Тур.	Max	Unit
Drain - source breakdown voltage	$I_D = 10 \ \mu A, \ V_{G1S} = V_{G2S} = 0$	V <sub>(BR)DSS</sub>	12			V
Gate 1 - source breakdown voltage	$+ I_{G1S} = 10 \text{ mA}, V_{G2S} = V_{DS} = 0$	+ V <sub>(BR)G1SS</sub>	7		10	V
Gate 2 - source breakdown voltage	$\pm I_{G2S} = 10 \text{ mA}, V_{G1S} = V_{DS} = 0$	± V <sub>(BR)G2SS</sub>	7		10	V

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Parameter	Test condition	Symbol	Min	Тур.	Max	Unit
Gate 1 - source leakage current	$+ V_{G1S} = 5 V, V_{G2S} = V_{DS} = 0$	+ I <sub>G1SS</sub>			20	nA
Gate 2 - source leakage current	$\pm V_{G2S} = 5 \text{ V}, V_{G1S} = V_{DS} = 0$	± I <sub>G2SS</sub>			20	nA
Drain - source operating current	$V_{DS} = V_{RG1} = 5 \text{ V}, V_{G2S} = 4 \text{ V}, R_{G1}$ = 56 k $\Omega$	I <sub>DSO</sub>	8	12	17	mA
Gate 1 - source cut-off voltage	$V_{DS} = 5 \text{ V}, V_{G2S} = 4, I_{D} = 20 \mu\text{A}$	V <sub>G1S(OFF)</sub>	0.3		1.0	V
Gate 2 - source cut-off voltage	$V_{DS} = V_{RG1} = 5 \text{ V}, R_{G1} = 56 \text{ k}\Omega, I_{D}$ = 20 $\mu$ A	V <sub>G2S(OFF)</sub>	0.3		1.2	V

#### **Amplifier 2**

Following data are valid for operating amplifier 2 (pin 6, 4, 2, 5) which is optimized for UHF applications

Parameter	Test condition	Symbol	Min	Тур.	Max	Unit
Drain - source breakdown voltage	$I_D = 10 \mu A, V_{G1S} = V_{G2S} = 0$	V <sub>(BR)DSS</sub>	12			V
Gate 1 - source breakdown voltage	$+ I_{G1S} = 10 \text{ mA}, V_{G2S} = V_{DS} = 0$	+ V <sub>(BR)G1SS</sub>	7		10	V
Gate 2 - source breakdown voltage	$\pm I_{G2S} = 10 \text{ mA}, V_{G1S} = V_{DS} = 0$	± V <sub>(BR)G2SS</sub>	7		10	V
Gate 1 - source leakage current	$+ V_{G1S} = 5 V, V_{G2S} = V_{DS} = 0$	+ I <sub>G1SS</sub>			20	nA
Gate 2 - source leakage current	$\pm V_{G2S} = 5 \text{ V}, V_{G1S} = V_{DS} = 0$	± I <sub>G2SS</sub>			20	nA
Drain - source operating current	$V_{DS} = V_{RG1} = 5 \text{ V}, V_{G2S} = 4 \text{ V}, R_{G1}$ = 56 k $\Omega$	I <sub>DSO</sub>	8	12	17	mA
Gate 1 - source cut-off voltage	$V_{DS} = 5 \text{ V}, V_{G2S} = 4, I_{D} = 20 \mu\text{A}$	V <sub>G1S(OFF)</sub>	0.3		1.0	V
Gate 2 - source cut-off voltage	$V_{DS} = V_{RG1} = 5 \text{ V}, R_{G1} = 100 \text{ k}\Omega, I_{D}$ = 20 $\mu\text{A}$	V <sub>G2S(OFF)</sub>	0.3		1.2	V

#### **Electrical AC Characteristics**

 $T_{amb}$  = 25 °C, unless otherwise specified

## **Amplifier 1**

 $V_{DS}=V_{RG1}=5~V,~V_{G2S}=4~V,~R_{G1}=56~k\Omega,~I_D=I_{DSO,}~f=1~MHz,~T_{amb}=25~^{\circ}C,~unless~otherwise~specified~Following~data~are~valid~for~operating~amplifier~1(pin~1,~3,~2,~5)~which~is~optimized~for~VHF~applications$ 

Parameter	Test condition	Symbol	Min	Тур.	Max	Unit
Forward transadmittance		ly <sub>21s</sub> l	23	28	33	mS
Gate 1 input capacitance		C <sub>issg1</sub>		2.5	3.0	pF
Feedback capacitance		C <sub>rss</sub>		20		fF
Output capacitance		C <sub>oss</sub>		0.9		pF
Power gain	$G_S = 2 \text{ mS}, B_S = B_{Sopt}, G_L = 0.5$ mS, $B_L = B_{Lopt}, f = 200 \text{ MHz}$	G <sub>ps</sub>		32		dB
	$G_S = 2 \text{ mS}, B_S = B_{Sopt}, G_L = 1 \text{ mS},$ $B_L = B_{Lopt}, f = 400 \text{ MHz}$	G <sub>ps</sub>		28		dB
	$G_S = 3.3 \text{ mS}, B_S = B_{Sopt}, G_L = 1$ mS, $B_L = B_{Lopt}, f = 800 \text{ MHz}$	G <sub>ps</sub>		22		dB
AGC range	$V_{DS} = 5 \text{ V}, V_{G2S} = 0.5 \text{ to 4 V}, f = 200$ MHz	G <sub>ps</sub>		50		dB
Noise figure	$G_S = G_L = 20 \text{ mS}, B_S = B_L = 0, f = 50 \text{ MHz}$	F		4.5	6.0	dB
	$G_S = 2 \text{ mS}, G_L = 1 \text{ mS}, B_S = B_{Sopt},$ f = 400 MHz	F		1.0	1.6	dB
	$G_S = 3.3 \text{ mS}, G_L = 1 \text{ mS}, B_S = B_{Sopt}, f = 800 \text{ MHz}$	F		1.5	2.3	dB

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Parameter	Test condition	Symbol	Min	Тур.	Max	Unit
Cross modulation	Input level for $k = 1 \% @ 0 dB AGC$ $f_w = 50 MHz, f_{unw} = 60 MHz$	X <sub>mod</sub>	90			dΒμV
	Input level for $k = 1 \% @ 40 dB$ AGC $f_w = 50 MHz$ , $f_{unw} = 60 MHz$	X <sub>mod</sub>	105			dΒμV

#### Remark on improving intermodulation behavior:

By setting  $R_{G1}$  smaller than 56  $k\Omega,$  typical value of  $I_{DSO}$  will raise and improved intermodulation behavior will be performed.

#### **Amplifier 2**

 $V_{DS}=V_{RG1}=5~V,~V_{G2S}=4~V,~R_{G1}=100~k\Omega,~I_{D}=I_{DSO,}~f=1~MHz,~T_{amb}=25~^{\circ}C,~unless~otherwise~specified~Following~data~are~valid~for~operating~amplifier~2~(pin~6,~4,~2,~5)~which~is~optimized~for~UHF~applications$ 

Parameter	Test condition	Symbol	Min	Тур.	Max	Unit
Forward transadmittance		ly <sub>21s</sub> l	27	31	35	mS
Gate 1 input capacitance		C <sub>issg1</sub>		1.9	2.3	pF
Feedback capacitance		C <sub>rss</sub>		20		fF
Output capacitance		C <sub>oss</sub>		0.9		pF
Power gain	$G_S = 2 \text{ mS}, B_S = B_{Sopt}, G_L = 0.5$ $mS, B_L = B_{Lopt}, f = 200 \text{ MHz}$	G <sub>ps</sub>		33		dB
	$G_S = 2 \text{ mS}, B_S = B_{Sopt}, G_L = 1 \text{ mS},$ $B_L = B_{Lopt}, f = 400 \text{ MHz}$	G <sub>ps</sub>		30		dB
	$G_S = 3.3$ mS, $B_S = B_{Sopt}$ , $G_L = 1$ mS, $B_L = B_{Lopt}$ , $f = 800$ MHz	G <sub>ps</sub>		25		dB
AGC range	$V_{DS} = 5 \text{ V}, V_{G2S} = 0.5 \text{ to 4 V}, f = 200$ MHz	G <sub>ps</sub>		50		dB
Noise figure	$G_S = G_L = 20 \text{ mS}, B_S = B_L = 0, f = 50 \text{ MHz}$	F		6.0	8.0	dB
	$G_S = 2 \text{ mS}, G_L = 1 \text{ mS}, B_S = B_{Sopt},$ f = 400  MHz	F		1.0	1.5	dB
	$G_S = 3.3 \text{ mS}, G_L = 1 \text{ mS}, B_S = B_{Sopt}, f = 800 \text{ MHz}$	F		1.3	2.0	dB
Cross modulation	Input level for k = 1 % @ 0 dB AGC $f_w = 50$ MHz, $f_{unw} = 60$ MHz	X <sub>mod</sub>	90			dΒμV
	Input level for $k = 1 \% @ 40 dB$ AGC $f_w = 50 MHz$ , $f_{unw} = 60 MHz$	X <sub>mod</sub>	100	105		dΒμV

#### Remark on improving intermodulation behavior:

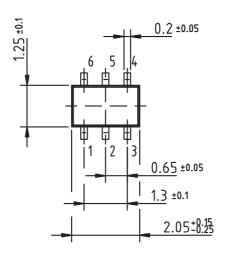
By setting  $R_{G1}$  smaller than 100  $k\Omega$ , e. g. 68  $k\Omega$  typical value of  $I_{DSO}$  will raise and improved intermodulation behavior will be performed.

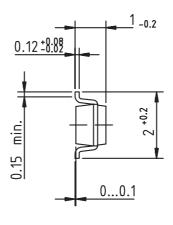
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# **Package Dimensions in mm**







14280

# **TSDF02830Y**

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## Ozone Depleting Substances Policy Statement

It is the policy of Vishay Semiconductor GmbH to

- 1. Meet all present and future national and international statutory requirements.
- 2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

Vishay Semiconductor GmbH has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

- 1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively
- 2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA
- 3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

Vishay Semiconductor GmbH can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

#### We reserve the right to make changes to improve technical design and may do so without further notice.

Parameters can vary in different applications. All operating parameters must be validated for each customer application by the customer. Should the buyer use Vishay Semiconductors products for any unintended or unauthorized application, the buyer shall indemnify Vishay Seminconductors against all claims, costs, damages, and expenses, arising out of, directly or indirectly, any claim of personal damage, injury or death associated with such unintended or unauthorized use.

> Vishay Semiconductor GmbH, P.O.B. 3535, D-74025 Heilbronn, Germany Telephone: 49 (0)7131 67 2831, Fax number: 49 (0)7131 67 2423

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